

Manual Update Sheet

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Document Being Updated: *TMS320C32 Addendum to the TMS320C3x User's Guide*
Literature Number Being Updated: SPRU132B

This Manual Update Sheet (SPRZ098) ships with the *TMS320C3x User's Guide* (SPRU031D) and the *TMS320C32 Addendum to the TMS320C3x User's Guide* (SPRU132B).

Page:	Change or Add:
2-2	In <i>Figure 2-1, TMS320C32 Functional Block Diagram</i> , the serial port pins (FSX0, DX0, CLKX0, FSR0, DR0, and CLKR0) are shown as unidirectional. They should be shown as bidirectional.
3-15	In <i>Table 3-8, Source Data Stream Structure</i> , the valid data entry for the word $m + 2$ is listed as SSSSSS6xh ^a . It should be SSSSSS6xh [‡] .
6-5	In subsection 6.7.1, <i>IDLE2 Power-Down Mode</i> , the last line of the third bulleted item should read "...control signals are in the inactive state."
7-17	In subsection 7.3.3, <i>16-Bit Wide Memory Interface</i> , on the fifth line of the first paragraph, the address pin A ₋₁ should be A ₋₁ .
7-18	In <i>Figure 7-12, Functional Diagram for 8-Bit Data Type Size and 16-Bit External Memory Width</i> , the STRBx_B3/A-1 external pin should be STRBx_B3/A ₋₁ .
7-20	In <i>Figure 7-13, Functional Diagram for 16-Bit Data Type Size and 16-Bit External Memory Width</i> , the STRBx_B3/A-1 external pin should be STRBx_B3/A ₋₁ .
7-21	In <i>Figure 7-14, Functional Diagram for 32-Bit Data Type Size and 16-Bit External Memory Width</i> , the STRBx_B3/A-1 external pin should be STRBx_B3/A ₋₁ .
7-22	On the fifth line of the first paragraph, the address pins A ₋₁ and A ₋₂ should be A ₋₁ and A ₋₂ , respectively.
7-23	In <i>Figure 7-16, Functional Diagram for 8-Bit Data Type Size and 8-Bit External Memory Width</i> , the STRBx_B3/A-1 external pin should be STRBx_B3/A ₋₁ , and the STRBx_B2/A-2 external pin should be STRBx_B2/A ₋₂ .
12-4	In <i>Figure 12-3, 'C32 Memory Map</i> , the Data Buffers are shown as (32 × 16-bit). They should be shown as (32K × 16-bit).

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